



**EXPEDITED PROCEDURE – EXAMINING GROUP 2814**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit:	2814
Filed:	December 8, 2000	Docket No.:	884.798US1
Title:	Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers		
Assignee:	Intel Corporation	Customer Number:	21186

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**RESPONSE UNDER 37 C.F.R. 1.116**

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In response to the Final Office Action mailed October 5, 2005, please consider the remarks as follows: